

MPSW3725



NPN Transistor

This device is designed for high current, low impedance line driver applications. Sourced from Process 26.

Absolute Maximum Ratings TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units	
V_{CEO}	Collector-Emitter Voltage	40	V	
V _{CBO}	Collector-Base Voltage	60	V	
V _{EBO}	Emitter-Base Voltage	6.0	V	
I _C	Collector Current - Continuous	1.2	A	
T _J , T _{stg}	Operating and Storage Junction Temperature Range	-55 to +150	°C	

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Thermal Characteristics TA = 25°C unless otherwise noted

Symbol	Characteristic	Max	Units
		MPSW3725	
P _D	Total Device Dissipation	1.0	W
	Derate above 25°C	8.0	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	50	°C/W

NOTES:

1) These ratings are based on a maximum junction temperature of 150 degrees C.

2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

(continued)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
OFF CHAR	RACTERISTICS					
V _{(BR)CEO}	Collector-Emitter Breakdown Voltage*	I _C = 10 mA, I _B = 0	40			V
V _{(BR)CES}	Collector-Emitter Breakdown Voltage	$I_C = 10 \mu A, V_{BE} = 0$	60			V
V _{(BR)CBO}	Collector-Base Breakdown Voltage	$I_C = 100 \mu A, I_{CE} = 0$	60			V
V _{(BR)EBO}	Emitter-Base Breakdown Voltage	$I_E = 10 \mu A, I_C = 0$	6.0			V
СВО	Collector Cutoff Current	$V_{CB} = 50 \text{ V}, I_E = 0$ $V_{CB} = 50 \text{ V}, I_E = 0, T_A = 100^{\circ}\text{C}$			100 10	nA μA
h _{FE}		I_C = 10 mA, V_{CE} = 1.0 V I_C = 100 mA, V_{CE} = 1.0 V I_{C} =100mA, V_{CE} =1.0 V, T_{A} =-55°C I_C = 300 mA, V_{CE} = 1.0 V	60 30 40		180	
			•			
		I _C = 300 mA, V _{CE} = 1.0 V I _C =500mA, V _{CE} =1.0 V, T _A =-55°C I _C = 800 mA, V _{CE} = 2.0 V I _C = 1.0 A, V _{CE} = 5.0 V	20 20 25			
VCE(sat)	Collector-Emitter Saturation Voltage	$I_C = 10 \text{ mA}, I_B = 1.0 \text{ mA}$ $I_C = 100 \text{ mA}, I_B = 10 \text{ mA}$ $I_C = 100 \text{ mA}, I_B = 30 \text{ mA}$ $I_C = 300 \text{ mA}, I_B = 30 \text{ mA}$ $I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$ $I_C = 800 \text{ mA}, I_B = 80 \text{ mA}$ $I_C = 1.0 \text{ A}, I_B = 100 \text{ mA}$			0.25 0.26 0.4 0.52 0.8 0.95	V V V V
V _{BE(sat)}	Base-Emitter Saturation Voltage	$\begin{array}{c} I_C = 10 \text{ mA, } I_B = 1.0 \text{ mA} \\ I_C = 100 \text{ mA, } I_B = 10 \text{ mA} \\ I_C = 300 \text{ mA, } I_B = 30 \text{ mA} \\ I_C = 500 \text{ mA, } I_B = 50 \text{ mA} \\ I_C = 800 \text{ mA, } I_B = 80 \text{ mA} \\ I_C = 1.0 \text{ A, } I_B = 100 \text{ mA} \\ \end{array}$			0.76 0.86 1.1 1.2 1.5 1.7	V V V V V
SMALL SI	GNAL CHARACTERISTICS					
Т	Current Gain - Bandwidth Product	$I_C = 50 \text{ mA}, V_{CE} = 10 \text{ V},$ f = 100 MHz	250			MHz
Cobo	Output Capacitance	$V_{CB} = 10 \text{ V}, I_{E} = 0,$ f = 1.0 MHz			25	pF
Cibo	Input Capacitance	$V_{EB} = 0.5 \text{ V}, I_{C} = 0,$ f = 1.0 MHz			100	pF

 $I_C = 500 \text{ mA}, I_{B1} = 50 \text{ mA}$

 $V_{CC} = 30 \text{ V}, I_{C} = 500 \text{mA}$

 $I_{B1} = I_{B2} = 50 \text{ mA}$

10

12

250

235

15

ns

ns

ns

ns

ns

Delay Time

Rise Time

Fall Time

Turn-off Time

Storage Time

 t_{d}

tr

t_{off}

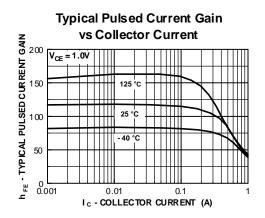
 $t_{\text{\tiny S}}$

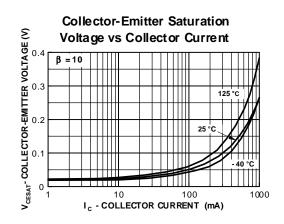
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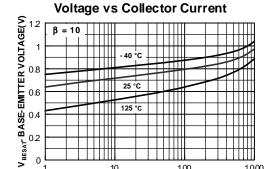
^{*}Pulse Test: Pulse Width $\leq\!300~\mu\text{s},$ Duty Cycle $\leq\!1.0\%$

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Typical Characteristics







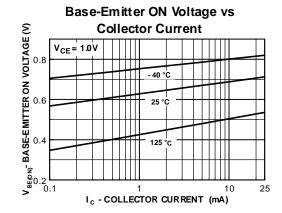
Ic - COLLECTOR CURRENT (mA)

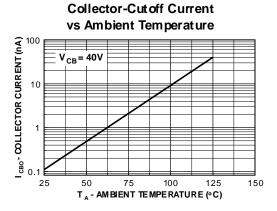
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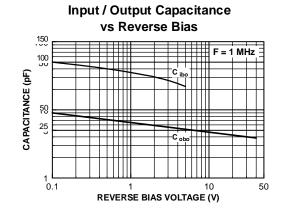
1000

0 L

Base-Emitter Saturation

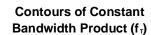


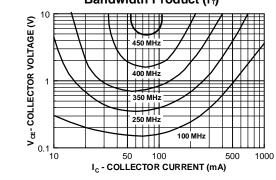




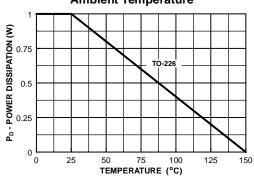
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Typical Characteristics (continued)



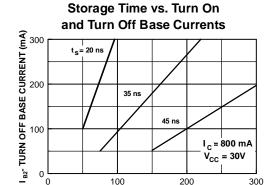


Power Dissipation vs Ambient Temperature

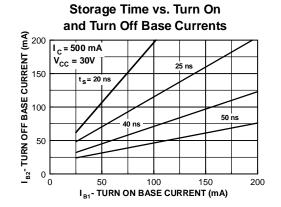


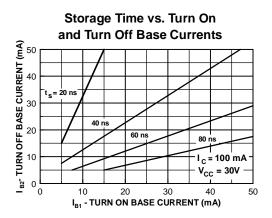
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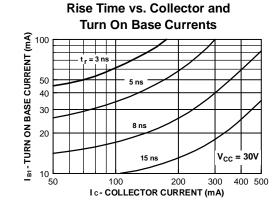
Typical Characteristics (continued)



I_{B1} - TURN ON BASE CURRENT (mA)

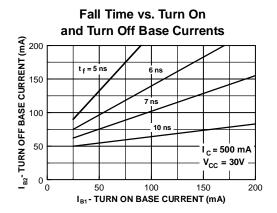


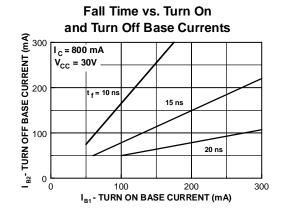


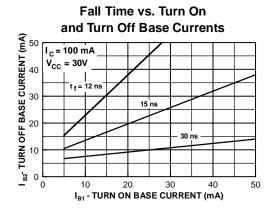


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Typical Characteristics (continued)







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Test Circuit

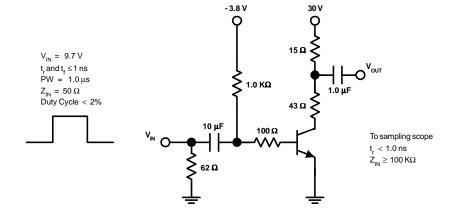


FIGURE 1: Switching Time Test Circuit (I $_{\rm c}$ = 500 mA, I $_{\rm B1}$ = 50 mA, I $_{\rm B2}$ = 50 mA)

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